

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. - 13. (Canceled)

14. (Currently Amended) A printer configured to print at least directly on a copper-clad substrate to facilitate inexpensively producing a printed circuit board, comprising:

an adjustable feeding mechanism for feeding at least a copper-clad substrate into the printer;

a printing mechanism, proximate to the adjustable feeding mechanism[[,]]; and

~~arranged to provide for printing~~ an inverse circuit image printed by the printing mechanism on the copper-clad substrate,

wherein the inverse circuit image is allowed to dry, the copper-clad substrate is immersed in a tinning solution to adhere a resist mask to an exposed, uninked copper to form a tinned circuit image, and the copper-clad substrate is etched to remove copper that forms the inverse circuit image.

15. (Original) The printer of claim 14 wherein the printer utilizes water-insoluble ink.

16. (Original) The printer of claim 14 wherein the printer utilizes India ink.

17. (Original) The printer of claim 14 wherein the adjustable feeding mechanism includes at least two settings; a first setting to feed paper through a printing process and a second setting to accommodate a copper-clad substrate having a predetermined size.

18. (Original) The printer of claim 17 wherein the at least two settings include a plurality of settings to accommodate a plurality of sizes of copper-clad substrates.

19. (Currently Amended) A printer configured to print at least directly on a copper-clad substrate to facilitate inexpensively producing a printed circuit board, comprising:

a flat-input feeder for feeding at least a copper-clad substrate into the printer;

a printing mechanism, proximate to the flat-input feeder; and

~~arranged to print an inverse circuit image printed by the printing~~
mechanism on the copper-clad substrate that is fed into the printer; and

wherein the inverse circuit image is allowed to dry, the copper-clad substrate is metalized to adhere a resist mask to an exposed, uninked copper to form a metalized circuit image, and the copper-clad substrate that has been metalized is etched to remove copper that forms the inverse circuit image.

20. (Original) The printer of claim 19 wherein the printer utilizes water-insoluble ink.

21. (Original) The printer of claim 19 wherein the printer utilizes India ink.

22. (Original) The printer of claim 19 wherein the flat-input feeder is adjustable to include at least two settings: a first setting to feed paper through a printing process and a second setting to accommodate a copper-clad substrate having a predetermined size.

23. (Original) The printer of claim 22 wherein the at least two settings include a plurality of settings that accommodate a plurality of sizes of copper-clad substrates.

24. (Original) The printer of claim 19 wherein the exposed, uninked copper is metalized to adhere a resist mark using at least one of: manganese, chromium, aluminum, iron, cobalt, nickel, tin, zinc, cadmium, palladium, and lead.

25. (Original) The printer of claim 19 wherein the exposed, uninked copper is metalized to adhere a resist mask using an alloy of at least one of: manganese, chromium, aluminum, iron, cobalt, tin, zinc, nickel, cadmium, palladium, and lead.

26. (Original) The printer of claim 19 wherein the exposed, uninked copper is metalized to adhere a resist mask using at least one of: soldering, electroplating and electroless plating.